

**Amendments to the Claims:**

1. (previously presented) A substrate for an unpackaged integrated circuit chip having surface mount contacts disposed thereon in a pattern, comprising:  
an insulating material; and  
a conductive material disposed over the insulating material, the conductive material comprising a plurality of contacts arranged in a pattern corresponding to the integrated circuit contact pattern, the conductive material comprising a conductive ring disposed around the periphery of the contact pattern, the conductive material comprising a first trace connected to said conductive ring and surrounding a selected one of said plurality of contacts, wherein the substrate contacts are coupleable to the integrated circuit chip surface mount contacts.
2. (original) The substrate according to Claim 1, wherein the conductive material comprises at least one conductive trace disposed proximate at least one contact.
3. (canceled)
4. (original) The substrate according to Claim 1, wherein the substrate contacts comprise wire bond pads, wherein the wire bond pads are coupleable to the integrated circuit chip surface mount contacts.
5. (original) The substrate according to Claim 1, wherein the insulating material comprises polyimide, fiberglass or a flexible dielectric material.
6. (original) The substrate according to Claim 1, wherein the insulating material includes a plurality of apertures disposed in the integrated circuit contact pattern.
7. (original) The substrate according to Claim 1 wherein the conductive material comprises Cu, Pt, Sn, Ni, Ag, Au, Cr, or combinations thereof.

8. (original) The substrate according to Claim 1, wherein the conductive material is formed by electro-less plating.
9. (previously presented) A package for an integrated circuit chip having surface mount contacts disposed thereon in a pattern, comprising:
- a substrate including an insulating material and a conductive material disposed over the insulating material, the conductive material comprising a plurality of contacts arranged in a pattern corresponding to the integrated circuit contact pattern, the conductive material comprising a conductive ring disposed around the periphery of the contact pattern, the conductive material comprising a first trace connected to said conductive ring and surrounding a selected one of said plurality of contacts, wherein the substrate contacts are coupleable to the integrated circuit chip surface mount contacts.
10. (original) The package according to Claim 9, wherein the conductive material comprises at least one conductive trace disposed proximate at least one contact.
11. (canceled)
12. (original) The package according to Claim 9, wherein the substrate contacts comprise wire bond pads, wherein the wire bond pads are coupleable to the integrated circuit chip surface mount contacts.
13. (original) The package according to Claim 9, further comprising an encapsulating insulating material disposed over the integrated circuit and substrate.
14. (original) The package according to Claim 13, further comprising a shielding material disposed over the encapsulating insulating material, the shielding material being electrically coupled to the conductive material solid ring.

15. (original) The package according to Claim 14, wherein the shielding material comprises an electrically conductive material.
16. (original) The package according to Claim 14, wherein the shielding material comprises a dissipative material having less than about 1 MΩ resistance.
17. (original) The package according to Claim 9, wherein the substrate insulating material comprises polyimide, fiberglass or a flexible dielectric material, and wherein the conductive material comprises Cu, Pt, Sn, Ni, Ag, Au, Cr, or combinations thereof.
18. (original) The package according to Claim 9, wherein the substrate insulating material includes a plurality of apertures disposed in the integrated circuit contact pattern.
19. (original) The package according to Claim 9, wherein the substrate conductive material is formed by electro-less plating.
20. (original) The package according to Claim 9, wherein the integrated circuit comprises a ball grid array, chip scale package, or flip-chip.
21. (original) An integrated circuit packaged in the package of Claim 9.

Claims 22-28 (canceled)

29. (previously presented) A packaged integrated circuit, comprising:  
a substrate including an insulating material and a conductive material disposed over the insulating material, the conductive material comprising a plurality of contacts, the conductive material further comprising a conductive ring disposed around the periphery of said plurality of contacts, the conductive material further comprising a trace connected to said conductive ring and surrounding a selected one of said plurality of contacts.

30. (canceled)

31. (previously presented) The packaged integrated circuit of Claim 29, wherein said trace surrounds selected contacts in said plurality of contacts.

32. (previously presented) The packaged integrated circuit of Claim 29, wherein said selected one of said plurality of contacts is a controlled impedance connection.

33. (previously presented) The packaged integrated circuit of Claim 1, wherein said first trace surrounds selected contacts in said plurality of contacts.

34. (previously presented) The packaged integrated circuit of Claim 1, wherein said selected one of said plurality of contacts is a controlled impedance connection.

35. (previously presented) The packaged integrated circuit of Claim 9, wherein said first trace surrounds selected contacts in said plurality of contacts.

36. (previously presented) The packaged integrated circuit of Claim 9, wherein said selected one of said plurality of contacts is a controlled impedance connection.